



# N-Channel 100 V (D-S) MOSFET

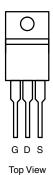
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)	
100	0.010 at V <sub>GS</sub> = 10 V	85 <sup>d</sup>	77	

## **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



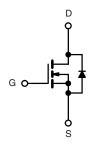
### TO-220AB



**Ordering Information:** SUP85N10-10P-GE3 (Lead (Pb)-free and Halogen-free)

## **APPLICATIONS**

Industrial



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATING</b>	<b>S</b> (T <sub>C</sub> = 25 °C, unless other	erwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	100		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C	. I <sub>D</sub>	85 <sup>d</sup>	A	
	T <sub>C</sub> = 70 °C		83		
Pulsed Drain Current		I <sub>DM</sub>	240	A	
Avalanche Current		I <sub>AS</sub>	60		
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	180	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	D	227 <sup>b</sup>	w	
	T <sub>A</sub> = 25 °C <sup>c</sup>	- P <sub>D</sub>	3.75		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.55		

## Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

Document Number: 64833 S11-2239-Rev. B, 14-Nov-11

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4.5		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ	
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50		
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
	В	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0080	0.0100	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0146	0.0185		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		70		S	
Dynamic <sup>b</sup>	•			•			
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 50 V, f = 1 MHz		4660		pF	
Output Capacitance	C <sub>oss</sub>			315			
Reverse Transfer Capacitance	C <sub>rss</sub>			150			
Total Gate Charge <sup>c</sup>	$Q_g$	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A		77	120	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			25			
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			20			
Gate Resistance	$R_{g}$	f = 1 MHz	0.25	1.2	2.4	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 50 V, $R_L$ = 0.67 $\Omega$ $I_D$ $\cong$ 75 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		12	20	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			25	40		
Fall Time <sup>c</sup>	t <sub>f</sub>			8	15		
Drain-Source Body Diode Characteri	stics T <sub>C</sub> = 25	${}_{\circ}C_{p}$					
Continuous Current	I <sub>S</sub>				85		
Pulsed Current	I <sub>SM</sub>				240	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 5 A, V <sub>GS</sub> = 0 V		0.8	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			74	115	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 5 A, dI/dt = 100 A/μs		6.7	10	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			250	400	nC	

## Notes:

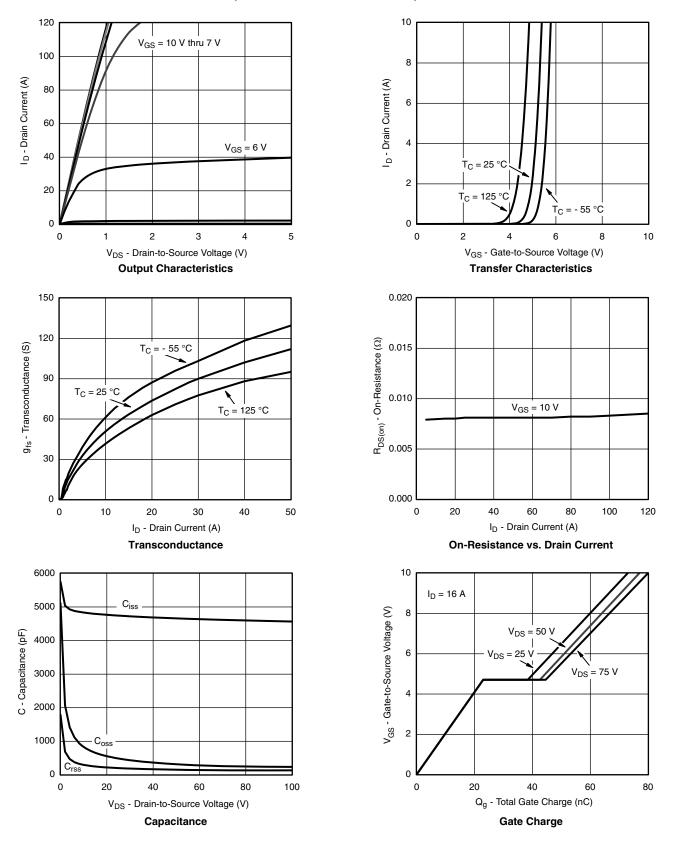
- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





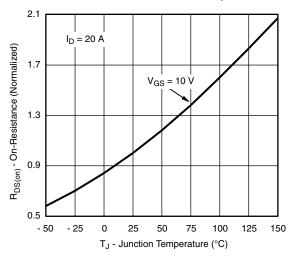
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



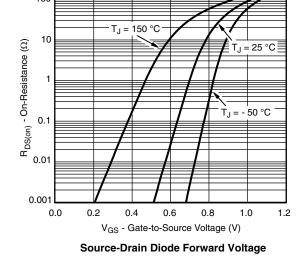
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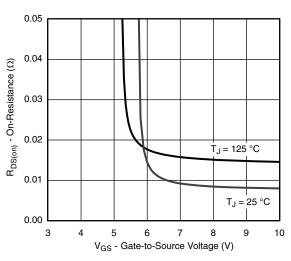
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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

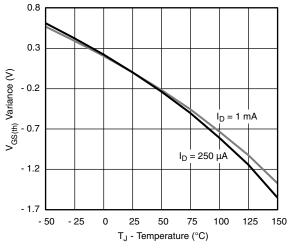


On-Resistance vs. Junction Temperature

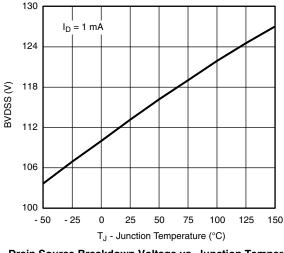




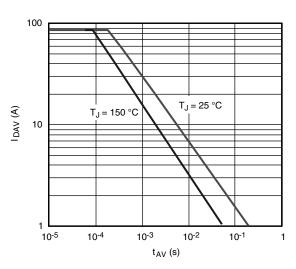
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



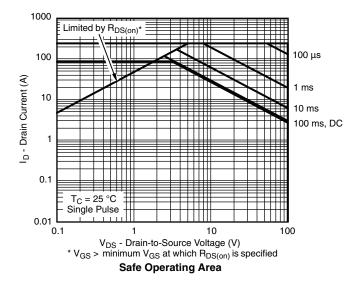
Drain Source Breakdown Voltage vs. Junction Temperature

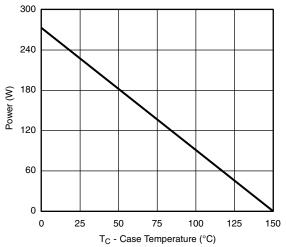


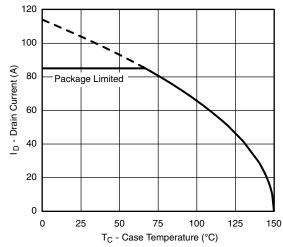
Single Pulse Avalanche Current Capability vs. Time



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







Power Derating, Junction-to-Case

**Current Derating\*** 

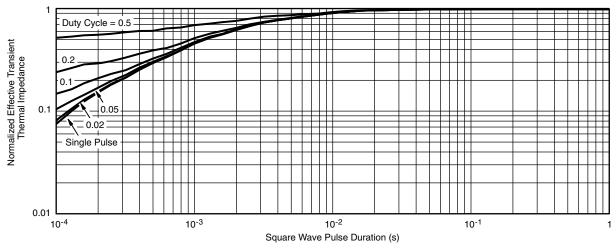
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<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heats inking is used. It is used to determine the current rating, when this rating falls below the package limit.

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

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